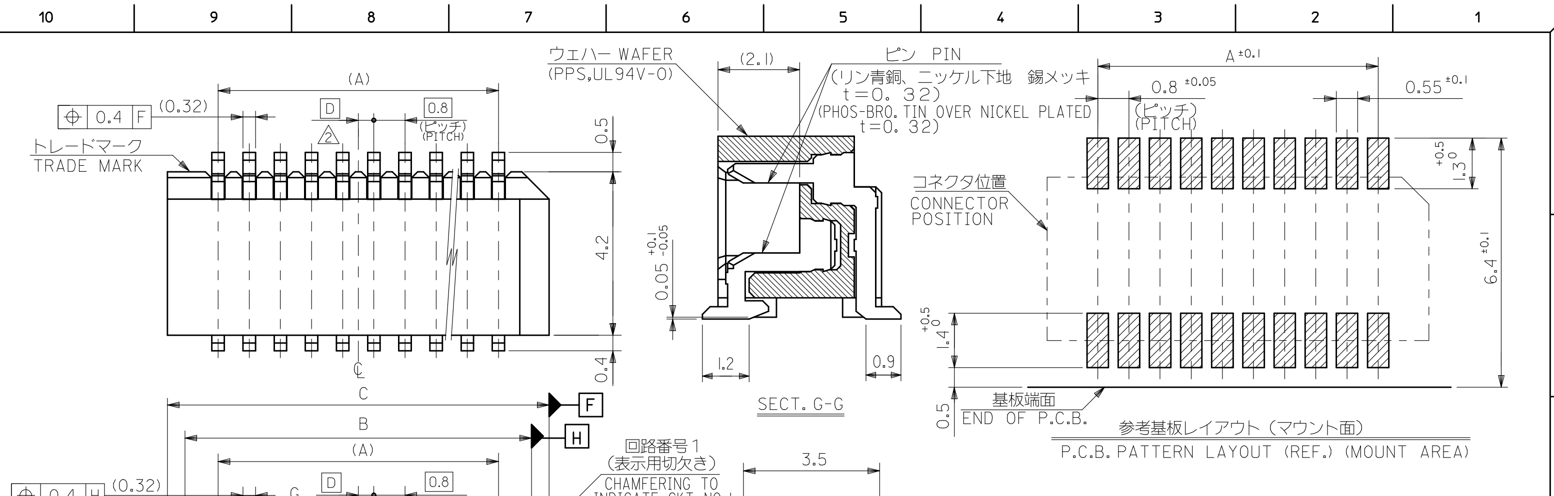
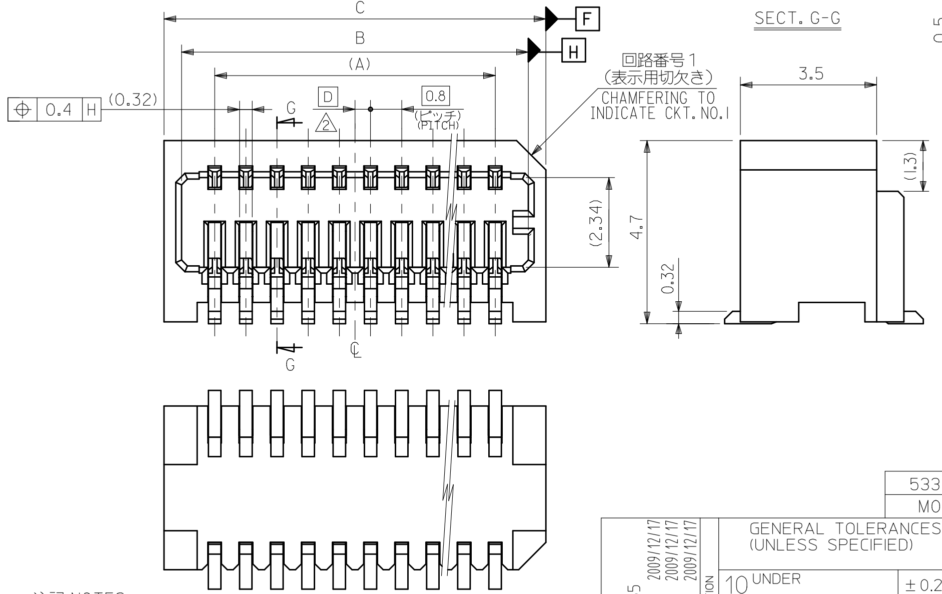




	0.4	17.8	16.9	15.2	53309-4029	40
	0.8	17.0	16.1	14.4	-3829	38
	0.4	16.2	15.3	13.6	-3629	36
	0.8	15.4	14.5	12.8	-3429	34
	0.4	14.6	13.7	12.0	-3229	32
	0.8	13.8	12.9	11.2	-3029	30
	0.4	13.0	12.1	10.4	-2829	28
	0.8	12.2	11.3	9.6	-2629	26
	0.4	11.4	10.5	8.8	-2429	24
	0.8	10.6	9.7	8.0	-2229	22
	0.4	9.8	8.9	7.2	-2029	20
	0.8	9.0	8.1	6.4	-1829	18
	0.4	8.2	7.3	5.6	-1629	16
	0.8	7.4	6.5	4.8	-1429	14
	0.4	6.6	5.7	4.0	-1229	12
53309-**29	0.8	5.8	4.9	3.2	53309-1029	10
MODEL NO.	D	C	B	A	MATERIAL NO.	極数CKT.

注記 NOTES

1. 嵌合相手：52465,52588シリーズ
   MATE WITH : 52465,52588 SERIES

△2 ウェハーの ℄ から隣接するピンの ℄ 迄の位置を示す。
   SHOW POSITION FROM ℄ OF WAFER TO ℄ OF ADJACENT PINS.

3. 本製品は 53309-**27 の鉛フリー品である。
   THIS PRODUCT IS LEAD FREE OF 53309-**27

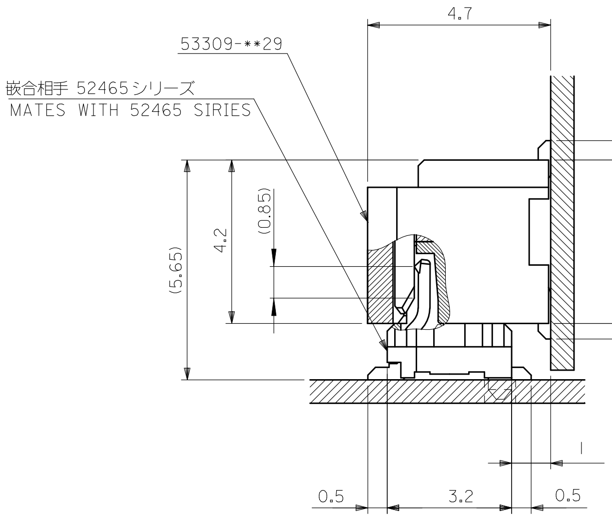
REV	DESCRIPTION
B	REVISED EC NO: J2010-1285 DRWN:YON002 2009/12/17 CH'KD:SMARUYAMA 2009/12/17 APPR:SMARUYAMA 2009/12/17

GENERAL TOLERANCES
(UNLESS SPECIFIED)

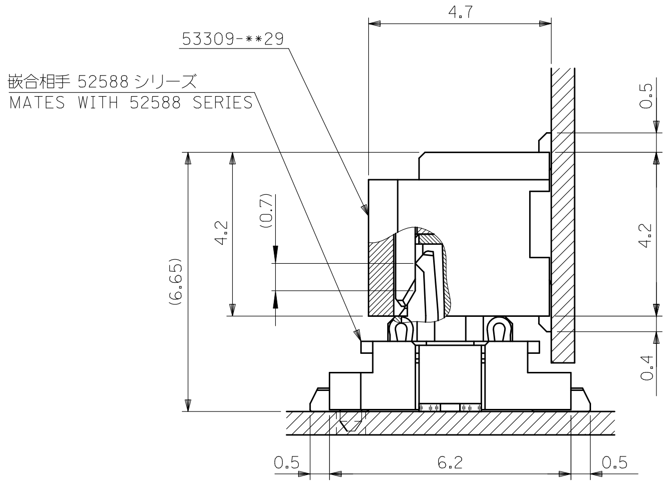
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
DRAWN BY M.NINOMIYA	DATE 2004/03/10	TITLE	0.8 B/B CONN.WAFER ASS'Y R/A SMT(WITHOUT BOSS)
CHECKED BY K.TOJO	DATE 2004/03/10		
APPROVED BY M.SASAO	DATE 2004/03/10		MOLEX INCORPORATED
MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-53309-011	SHEET NO. 1 OF 2
SIZE A3			



嵌合状態図（参考）
MATED DRAWING(REF.)



嵌合状態図（参考）
MATED DRAWING(REF.)

REVISED
EC NO: J2010-1285
DRWN:YON002 2009/12/17
CH'KD:SMARUYAMA 2009/12/17
APPR:SMARUYAMA 2009/12/17
DESCRIPTION
B
REV

GENERAL TOLERANCES
(UNLESS SPECIFIED)

10 UNDER	± 0.2
10 OVER 30 UNDER	± 0.25
30 OVER	± 0.3
ANGULAR ±3 °	

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY
SCALE

DESIGN UNITS
METRIC
THIRD ANGLE PROJECTION

DRAWN BY M.NINOMIYA	DATE 2004/03/10
CHECKED BY K.TOJO	DATE 2004/03/10
APPROVED BY M.SASAO	DATE 2004/03/10

TITLE
0.8 B/B CONN.WAFER ASS'Y
R/A SMT(WITHOUT BOSS)

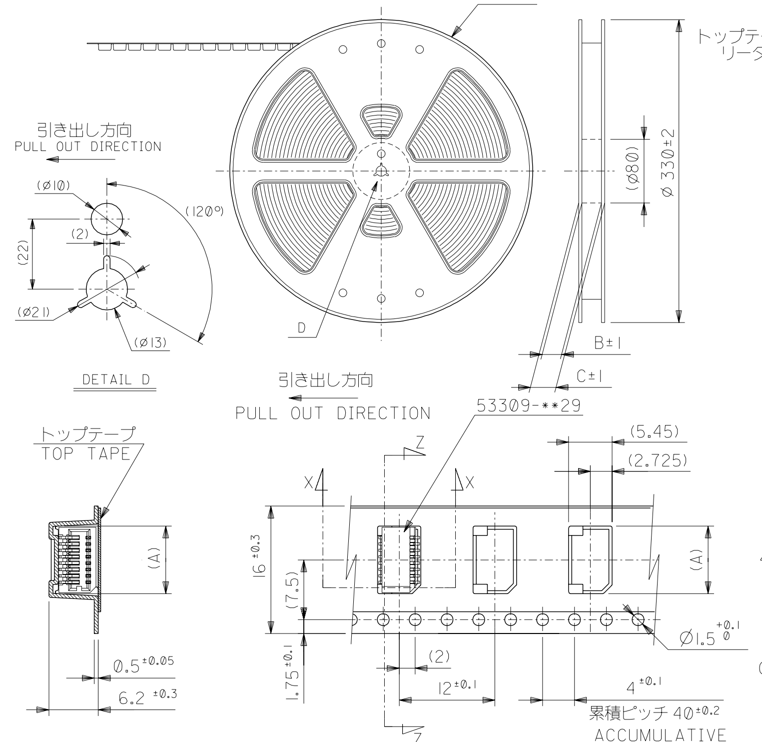
molex MOLEX INCORPORATED

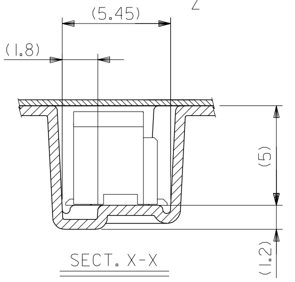
MATERIAL NO.
SEE SHEET 1
DOCUMENT NO.
SD-53309-011
SHEET NO.
2 OF 2
SIZE
A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

DWG. NO. SD-53309-012

DIMENSIONS IN METRIC DO NOT SCALE DRAWING :MM



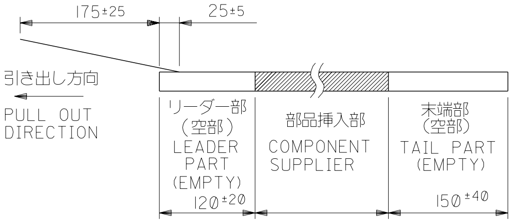


１６mm幅キャリアテープ
16mm WIDTH CARRIER TAPE

注記 NOTES

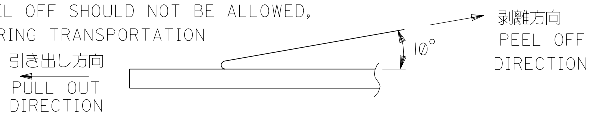
1. 梱包数量：１０００個／リール NUMBER OF CONNECTORS:1000PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH

トップテープ TOP TAPE リーダー部 LEADER PART　トップテープ TOP TAPE 未接着部 NON-BONDED PART



3. トップテープの剥離強度：（剥離方向は下図参照）
Ｏ。１Ｎ～１。３Ｎ ｛１０ｇｆ～１３０ｇｆ｝尚、本規格値は、出荷時に適用。
（但し、輸送時に剥離が発生しない事。）

PEELING OFF FORCE OF TOP TAPE
0.1N～1.3N{10gf ～130gf} (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLITED AT SHIPMENT
PEEL OFF SHOULD NOT BE ALLOWED,
DURING TRANSPORTATION



4. 材料
キャリアテープ：ポリプロピレン（ＰＰ）
トップテープ：ＰＥＴ，ＰＥ，ＰＥＦ
リール：ポリスチレン（ＰＳ）
<リサイクル材を含む>

MATERIAL
CARRIER TAPE:POLYPROPYLENE
TOP TAPE:PET,PE,PEF
REEL:POLYSTYRENE(PS)
<RECYCLE MATERIAL CONTAINED>

5. 本製品は 53309-**91 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53309-**91.

キャリアテープ幅 CARRIER TAPE WIDTH	C	B	(A)	MATERIAL NO.	極数 CIRCUIT
16	21.4	17.4	9.3	53309-1870	18
			8.5	53309-1670	16
			7.7	53309-1470	14
			6.9	53309-1270	12
			6.1	53309-1070	10

53309-**70	
MODEL NO.	
角度 ANGLE	±3°
30 以上 OVER	±0.3
10 以上 OVER 30 未満 UNDER	±0.25
10 未満 UNDER	±0.2
一般公差 GENERAL TOLERANCES	

記号 LTR	変更内容 REVISION RECORD	DR. CHK.	日付 DATE
0	新規作成 RELEASED (J2004-2995)	M.N K.T	'04/03/10

材料 MATERIAL: 注記参照 SEE NOTES
仕上げ FINISH: —//—
適用電線範囲 WIRE RANGE: —//—
被覆外径 INS. RANGE: —//—
DRAWN BY '04/03/10 M.NINOMIYA
CHK'D BY '04/03/10 K.TOJO
APP'D BY '04/03/10 M.SASAO
尺度 SCALE —//—

molex MOLEX-JAPAN CO.,LTD.
日本モレックス株式会社

REVISE ONLY ON CAD SYSTEM

TITLE 名称
0.8 B+B Conn Wafer Assy
RA SMT Without Boss
Embstp Pkg
-LEAD FREE-

DWG. NO. (SHEET 1 OF 2) SD-53309-012
REV 0

SD-53309-012.S01

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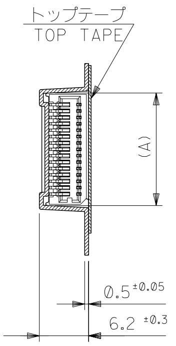
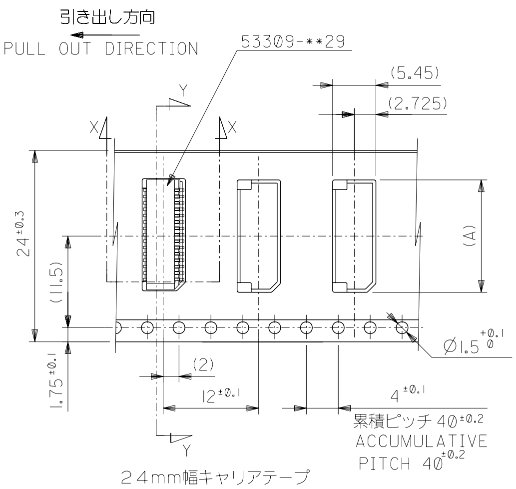
EN-01C(032)MXJ-32

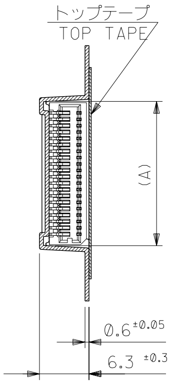
DWG. NO. SD-53309-012



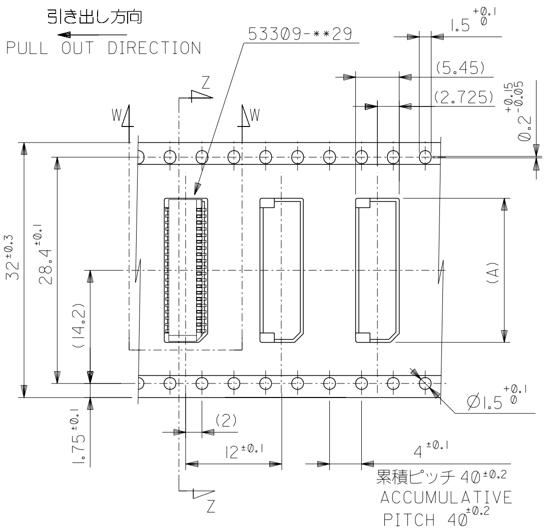
SECT. Y-Y



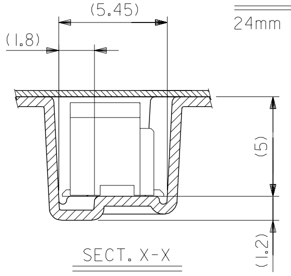
24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE



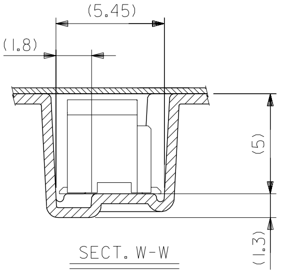
SECT. Z-Z



32mm幅キャリアテープ
32mm WIDTH CARRIER TAPE



SECT. X-X



SECT. W-W

キャリアテープ幅 CARRIER TAPE WIDTH	C	B	(A)	MATERIAL NO.	極数 CIRCUIT
32	37.4	33.4	18.1	53309-4070	40
			17.3	53309-3870	38

キャリアテープ幅 CARRIER TAPE WIDTH	C	B	(A)	MATERIAL NO.	極数 CIRCUIT
24	29.4	25.4	16.5	53309-3670	36
			15.7	53309-3470	34
			14.9	53309-3270	32
			14.1	53309-3070	30
			13.3	53309-2870	28
			12.5	53309-2670	26
			11.7	53309-2470	24
			10.9	53309-2270	22
			10.1	53309-2070	20

53309-**70	
MODEL NO.	
角度 ANGLE	±3°
30 以上 OVER	±0.3
10 以上 OVER 30 未満 UNDER	±0.25
10 未満 UNDER	±0.2
一般公差 GENERAL TOLERANCES	

記号 LTR	変更内容 REVISION RECORD	DR. CHK.	日付 DATE
0	新規作成 RELEASED (J2004-2995)	M.N K.T	'04/03/10

材料 MATERIAL	SHEET 1 OF 2参照 REFER TO SHEET 1 OF 2
仕上げ FINISH	—//—
適用電線範囲 WIRE RANGE	—//—
被覆外径 INS. RANGE	—//—
DRAWN BY '04/03/10 M.NINOMIYA	CHK'D BY '04/03/10 K.TOJO
APP'D BY '04/03/10 M.SASAO	尺度 SCALE —//—

MOLEX-JAPAN CO.,LTD.
日本モレックス株式会社

REVISE ONLY ON CAD SYSTEM

TITLE 名称
0.8 BtB Wafer Assy
RA SMT Without Boss
Embstp Pkg
-LEAD FREE-

DWG. NO.(SHEET 2 OF 2) SD-53309-012
REV 0

:MM DIMENSIONS IN METRIC DO NOT SCALE DRAWING

SD-53309-012.S02

EN-01C(032)MXJ-32